

Technical Data Sheet**1.4 mm Height Subminiature , Axial Flat Top View LED****28-21SDRC/S530-XX/XXX****Features**

- Package in 12mm tape on 7" diameter reels.
- Compatible with automatic placement equipment.
- EIA Std. package.
- Mono-color type.
- Pb-free.
- RoHS refer to SMD A type SGS report.

Descriptions

- The 28-21 SMD taping is much smaller than leaded components .Thus enable smaller board size. Higher packing density. Reduced storage space and finally smaller equipment to be obtained.
- Besides, light weight makes them ideal for miniature applications.
- Furthermore by automation assembly machines the accuracy is anticipated.

Applications

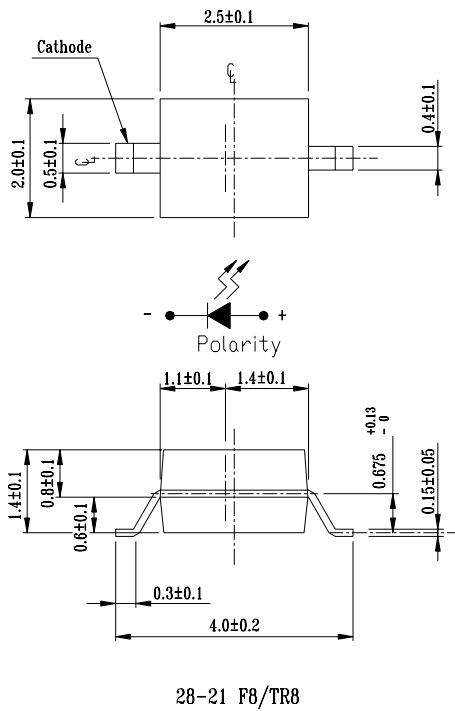
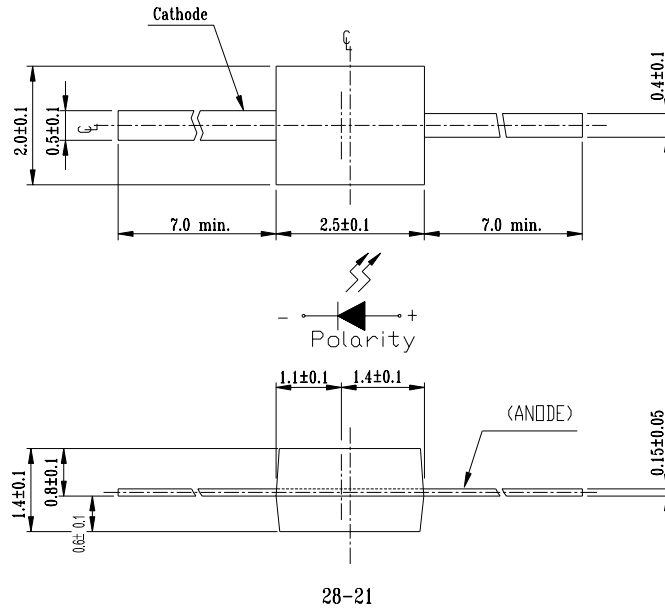
- Small indicator for indoor applications.
- Flat backlight for LCD, switches and symbols.
- Indicator and backlight in office equipment.
- Indicator and backlight for battery driven equipment.
- Indicator and backlight for audio and video equipment.
- Automotive : backlighting in dashboards and switches
- Telecommunication : indicator and backlighting in telephone and fax.

**Device Selection Guide**

Part No.	Chip		Lens Color
	Material	Emitted Color	
28-21SDRC/S530-XX/XXX	AlGaInP	Deep-Red	Water Clear

28-21SDRC/S530-XX/XXX

Package Outline Dimensions



Note :
 Tolerances unless dimension ±0.1
 Angle ±5
 Unit : mm

Note: Tolerances Unless Dimension is ±0.1mm , Unit = mm

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +100	°C
Electrostatic Discharge	ESD	2000	V
Power Dissipation	P _d	60	mW
Peak Forward Current(Duty 1/10 @ 1KHz)	I _{FP}	60	mA
Soldering Temperature	T _{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

28-21SDRC/S530-XX/XXX

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Chip Rank	MIN.	TYP.	MAX.	Unit	Condition			
Luminous Intensity	I _v	A2	----	2.00	----	mcd	I _F =2mA			
			12.0	21.0	----		I _F =20mA			
		A3	----	2.00	----		I _F =2mA			
			20.0	27.0	----		I _F =20mA			
		A4	----	2.00	----		I _F =2mA			
			24.0	34.0	----		I _F =20mA			
		A5	----	2.50	----		I _F =2mA			
			32.0	43.0	----		I _F =20mA			
		A6	----	3.00	----		I _F =2mA			
			40.0	54.0	----		I _F =20mA			
		Viewing Angle	2θ 1/2	----	----		150	----	deg	I _F =20mA
		Peak Wavelength	λ _p	----	----		650	----	nm	
Dominant Wavelength	λ _d	----	----	639	----	nm				
Spectrum Radiation Bandwidth	△λ	----	----	20	----	nm				
Forward Voltage	V _F	----	1.7	2.0	2.4	V				
Reverse Current	I _R	----	----	----	10	μA	V _R =5V			

*28-21SDRC/S530-XX / XXX

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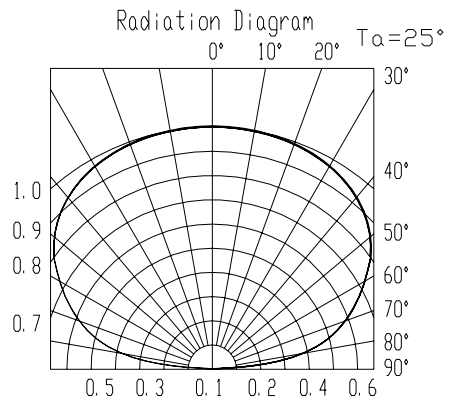
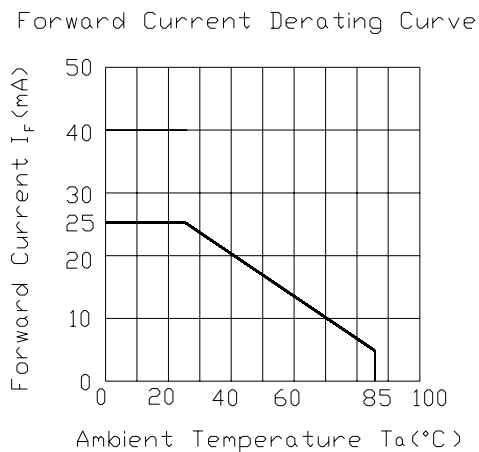
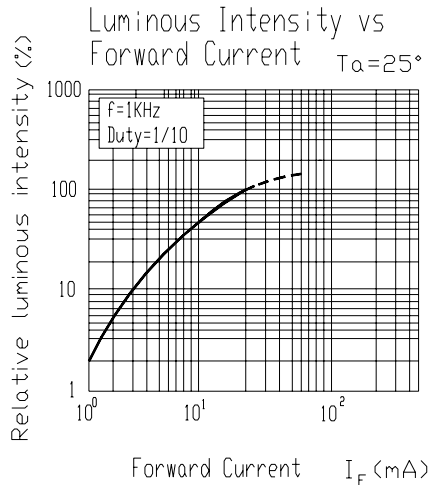
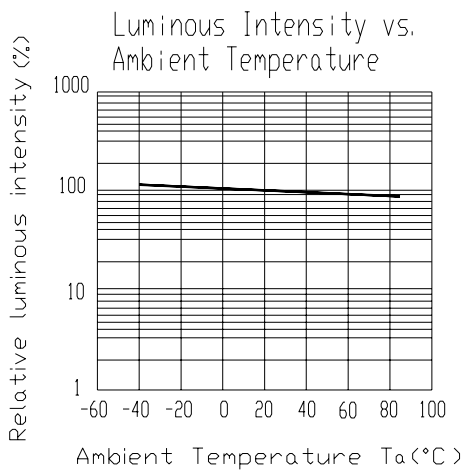
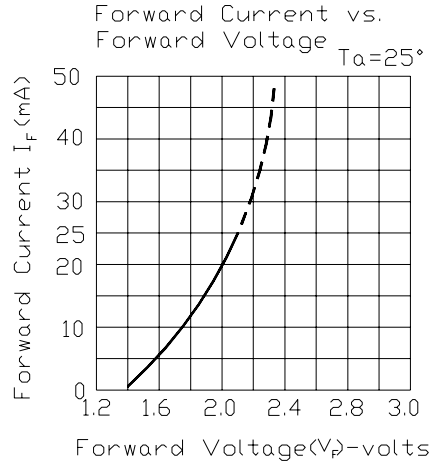
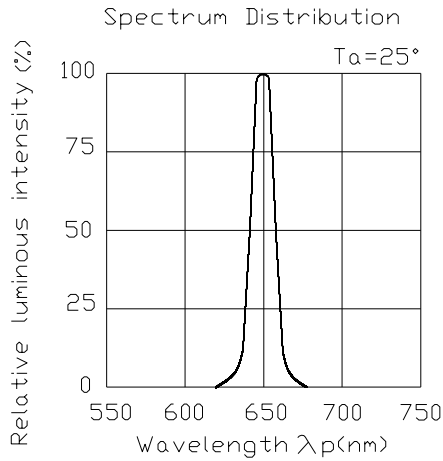
1:Chip Rank

2:Packing Method:

(1) None,F8 : Bulk

(2) TR8 : Taping

Typical Electro-Optical Characteristics Curves

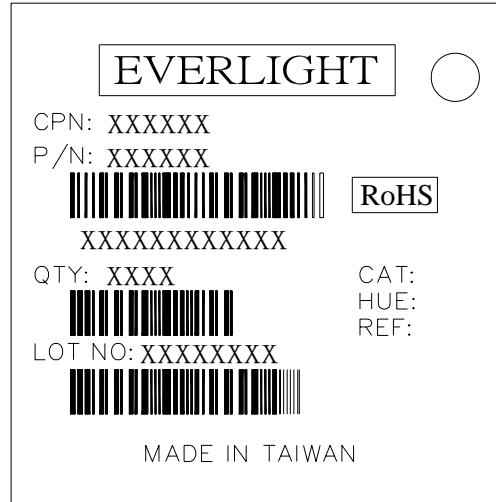


Label explanation

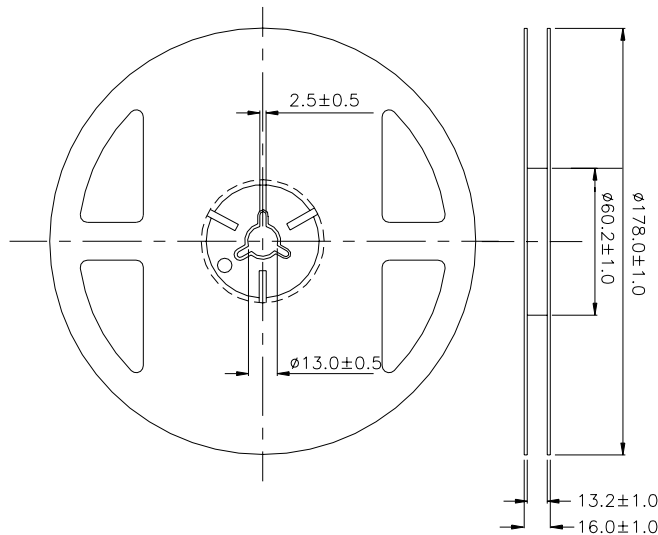
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank

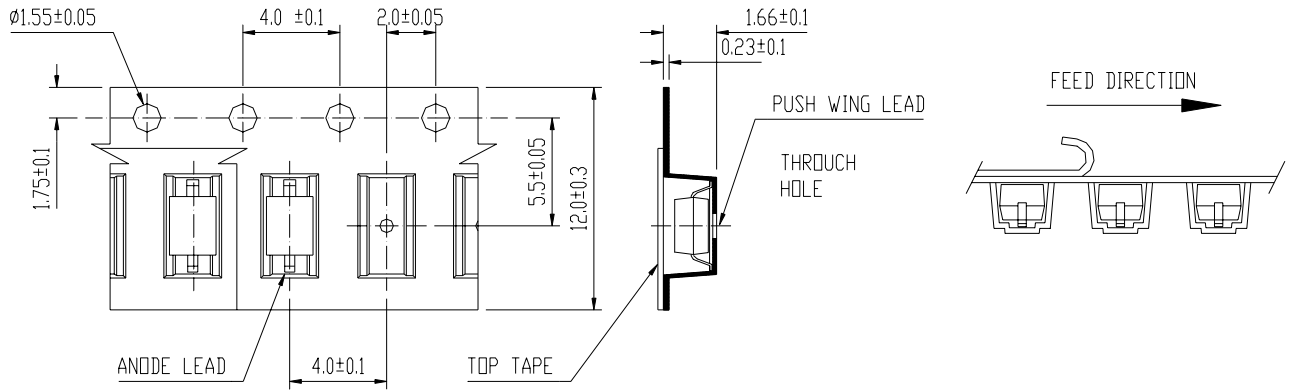


Reel & Carrier Tape Dimensions

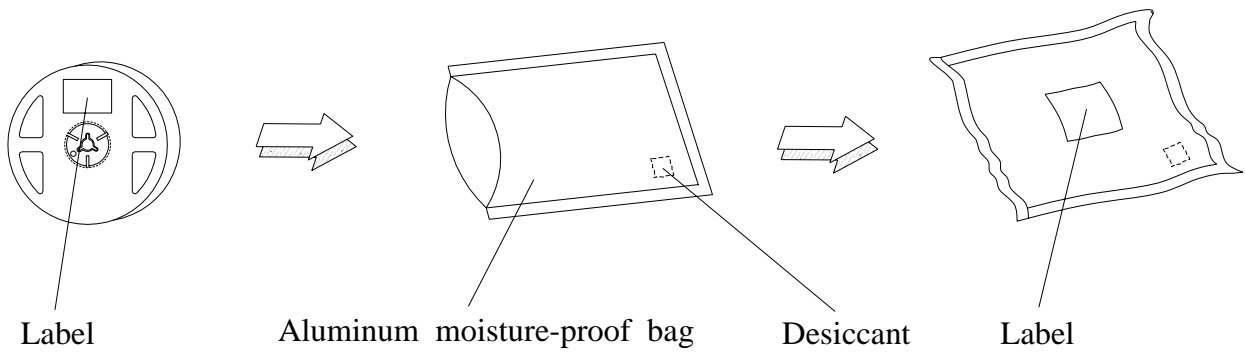


Note: The tolerances unless mentioned are ± 0.1 , unit=mm.

Loaded quantity per reel 1000 PCS/reel



Moisture Resistant Packaging



Note: Tolerances Unless Dimension is $\pm 0.1\text{mm}$, Unit = mm

Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level :

LTPD : 10 %

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C ±5°C Min. 5 sec.	6 Min.	22 Pcs.	0/1
2	Temperature Cycle	H : +100°C 15 min. § 5 min. L : -40°C 15 min.	300 Cycles	22 Pcs.	0/1
3	Thermal Shock	H : +100°C 5 min. § 10 sec. L : -10°C 5 min.	300 Cycles	22 Pcs.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 Pcs.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 Pcs.	0/1
6	DC Operating Life	I _F = 20 mA	1000 Hrs.	22 Pcs.	0/1
7	High Temperature / High Humidity	85°C / 85% RH	1000 Hrs.	22 Pcs.	0/1

Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less..

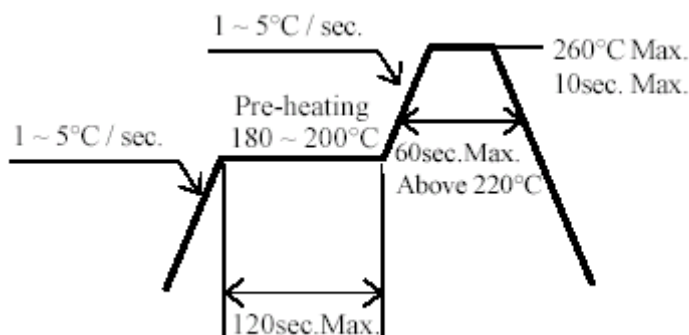
2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times

3.3 When soldering, do not put stress on the LEDs during heating.

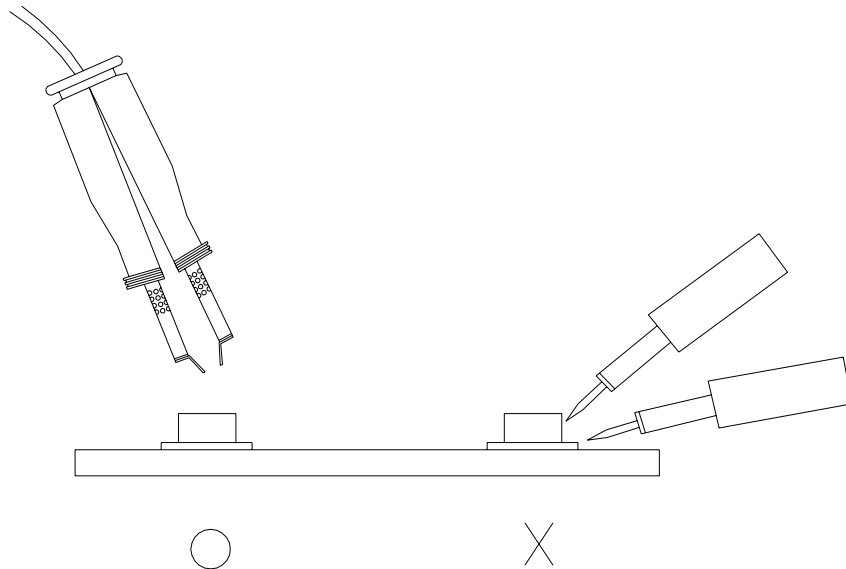
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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